

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	25	(29/852).ccls. and (via) and (paste) and (grind\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:07
L7	22	(29/852).ccls. and (via with fill\$3) and (paste) and (grind\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:06
L8	21	(29/852).ccls. and (via) and (paste) and (grind\$3) and plat\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:07
L9	16	(29/852).ccls. and (via) and (paste) and (grind\$3) and plat\$3 and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:07
L10	16	(29/852).ccls. and (via) and fill\$3 and (paste) and (grind\$3) and plat\$3 and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:08
L11	10	(29/852).ccls. and (via) and fill\$3 with (paste) and (grind\$3) and plat\$3 and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:09
L12	6	(29/830,831).ccls. and (via) and fill\$3 with (paste) and (grind\$3) and plat\$3 and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:09
L13	8	(29/846,847,853).ccls. and (via) and fill\$3 with (paste) and (grind\$3) and plat\$3 and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:10
L14	18	(174/257-259,264).ccls. and (via) and fill\$3 with (paste) and (grind\$3) and plat\$3 and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:11
L15	6	(427/97.2).ccls. and (via) and fill\$3 with (paste) and (grind\$3) and plat\$3 and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:11
S1	1	(kim-bong-suck).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 09:59
S2	1	(kim-gye-soo).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:21
S3	3	(kim-jong-hyung).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:30
S4	2	NMBI	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:31
S5	1	NMBI adj method	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:32

S6	6991	AGP	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:32
S7	173	AGP and bump	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:32
S8	73	AGP and bump and interconnect\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:33
S9	5	AGP and bump and interconnect\$3 and copper	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:34
S10	489	(stack\$3 near via) and interconnect\$3 and copper	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:35
S11	150	(stack\$3 near via) and interconnect\$3 and copper and (printed adj (wiring or circuit) adj board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:35
S12	85	(stack\$3 near via) and interconnect\$3 and copper and (printed adj (wiring or circuit) adj board) and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:35
S13	6	(stack\$3 near via) and interconnect\$3 and copper and (printed adj (wiring or circuit) adj board) and laser and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:46
S14	1194	(stack\$3 near via) and interconnect\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:46
S15	9	(stack\$3 near via) and interconnect\$3 and copper and laser and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:47
S16	1	(stack\$3 adj via adj hole) and interconnect\$3 and copper and laser and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:47
S17	81	(stack\$3 adj via adj hole)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:48
S18	35	(stack\$3 adj via adj hole) and laser	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/12 13:48
S19	3	(stack\$3 adj via adj hole) and laser and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/13 06:51
S20	16	(stack\$3 adj via) and laser and paste and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/13 06:51

S21	81	("2926340" "3436819" "3465435" "3516156" "3617817" "3770529" "3775844" "3867759" "3999004" "4030190" "4109377" "4152988" "4237606" "4258468" "4322778" "4443278" "4546065" "4567062" "4683653" "4685210" "4702785" "4706162" "4721831" "4734818" "4736521" "4772346" "4860165" "4867935" "4916260" "4933045" "4935844" "4954313" "4970106" "4972253" "5006923" "5011725" "5065284" "5073840" "5080966" "5087413" "5118643" "5142775" "5182632" "5216207" "5242713" "5254191" "5271887" "5276455" "5280414" "5282312" "5283104" "5284548" "5293025" "5300735" "5316985" "5329695" "5337466" "5349743" "5371654" "5396034" "5403420" "5450290" "5473194" "5480048" "5499442" "5543661" "5545429" "5570504" "5583321" "5590460" "5591941" "5604673" "5615477" "5619791" "5640049" "5710071" "Re35064").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 06:54
S22	21	("4970106").URPN.	USPAT	OR	ON	2005/10/13 07:09
S23	1	("4622058").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 07:19
S24	33	("5329695").URPN.	USPAT	OR	ON	2005/10/13 07:26
S25	3705	via and (laser or drill) and paste and (grind\$3 or machin\$3)	USPAT	OR	ON	2005/10/13 07:26
S26	2715	via and (laser or drill) and plat\$3 and paste and (grind\$3 or machin\$3)	USPAT	OR	ON	2005/10/13 07:27
S27	949	(interconnect\$3) and via and (laser or drill) and plat\$3 and paste and (grind\$3 or machin\$3)	USPAT	OR	ON	2005/10/13 07:27

S28	50	(interconnect\$3) and via and (laser or drill) and plat\$3 and (paste with (grind\$3 or machin\$3))	USPAT	OR	ON	2005/10/13 07:27
S29	17	(interconnect\$3) and (via with (laser or drill)) and plat\$3 and (paste with (grind\$3 or machin\$3))	USPAT	OR	ON	2005/10/13 07:28
S30	15	(interconnect\$3) and (via with (laser)) and plat\$3 and (paste with (grind\$3 or machin\$3))	USPAT	OR	ON	2005/10/13 07:29
S31	0	(interconnect\$3) and (via with (laser)) and plat\$3 and (paste with (grind\$3))	USPAT	OR	ON	2005/10/13 07:30
S32	59	(interconnect\$3) and (via with (laser)) and plat\$3 and paste and grind\$3	USPAT	OR	ON	2005/10/13 07:55
S33	30	(PCB or ((circuit or wiring) adj board)) and (interconnect\$3) and (via with (laser)) and plat\$3 and paste and grind\$3	USPAT	OR	ON	2005/10/13 07:31
S34	59	(interconnect\$3) and (via with (laser)) and plat\$3 and paste and grind\$3	USPAT	OR	ON	2005/10/13 08:09
S35	58	("4899921" "5138434" "5299092" "5437915" "5495667" "5543658" "5686317" "5851911" "5888883" "5897337" "6060373" "6080602" "6087845" "6097087" "6107109" "6114240" "6118179" "6130111" "6153448" "6169329" "6177295" "6221751" "6233185" "6235554" "6252299" "6271056" "6281131" "6294837" "6303981" "6303997" "6310390" "6313531" "6314013" "6326242" "6326698" "6330158" "6338980" "6340845" "6359456" "6362529" "6368896" "6368930" "6372624" "6384487" "6400172" "6440772" "6441483" "6451624" "6465877" "6472735" "6482576" "6482674" "6501165" "6506625" "6507114" "6577013" "6582992" "6614104").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 07:59

S36	76	(interconnect or interconnected or interconnecting or interconnection) and (via with (laser)) and (plated or plating) and paste and (lapp or lapped or lapping or grind or grinded or grinding)	USPAT	OR	ON	2005/10/13 08:11
S37	12	(interconnect or interconnected or interconnecting or interconnection) and (via with (laser)) with (plated or plating) and paste and (lapp or lapped or lapping or grind or grinded or grinding)	USPAT	OR	ON	2005/10/13 08:19
S38	110	(interconnect or interconnected or interconnecting or interconnection) and (via with (laser)) and paste and (lapp or lapped or lapping or grind or grinded or grinding)	USPAT	OR	ON	2005/10/13 08:33
S39	1	("5252754").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/10/13 08:30
S40	10	(interconnect or interconnected or interconnecting or interconnection) and (via with (laser)) and paste same (lapp or lapped or lapping or grind or grinded or grinding)	USPAT	OR	ON	2005/10/13 08:34
S41	24	(via with (laser)) and paste same (lapp or lapped or lapping or grind or grinded or grinding)	USPAT	OR	ON	2005/10/13 08:37
S42	10	(multilayer or multilayered) and (via with (laser)) and paste same (lapp or lapped or lapping or grind or grinded or grinding)	USPAT	OR	ON	2005/10/13 12:55
S43	45	("5744758").URPN.	USPAT	OR	ON	2005/10/13 08:40
S44	39	("3264402" "4372804" "4383363" "4648179" "4678963" "4865888" "5046238" "5326966" "5346750" "5359259" "5374469" "5407511" "5440075" "5478972" "5480503" "5481795" "5484647" "5498467" "5576519" "5595943" "5652042" "5707925" "5719354" "5744758" "5860818" "5914358" "5937725" "5950306" "5956843" "6051918" "6137054" "6143116" "6197407" "6224965" "6242079" "6329610" "6353189" "6365843").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/13 08:44

S45	18	("5956843").URPN.	USPAT	OR	ON	2005/10/13 08:52
S46	155	(multilayer or multilayered) and (via with (laser) with copper)	USPAT	OR	ON	2005/10/13 13:00
S48	12225	via and fill\$3 and paste and viscosity	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:02
S49	2342	via and fill\$3 and paste with viscosity	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:04
S51	3	via and fill\$3 and paste with viscosity with "dPa.s"	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:05
S52	3	via and fill\$3 and paste with viscosity same "dPa.s"	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:05
S53	4	via and fill\$3 and paste with viscosity and "dPa.s"	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:06
S54	520	(via with fill\$3) and (paste with viscosity)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:07
S55	65	(via with fill\$3) and (paste with viscosity) and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:07
S56	2	(via with fill\$3) and (paste with viscosity) and (grind\$3 with (buff or belt))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:21
S57	7	(via same fill\$3) and (paste with viscosity) and (grind\$3 with (buff or belt))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 12:05
S58	22	(paste with viscosity) and (grind\$3 with (buff or belt))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:42
S59	10	(paste with viscosity with "dPa")	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:22
S62	371	("dPa" with viscosity)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:43
S63	94	("dPa" with viscosity) and paste	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:43
S64	45	("dPa" with viscosity) and paste and via	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:51
S65	19	("dPa" with viscosity) and paste and via and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:51

S68	26	("dPa" with viscosity) and paste and via and fill\$2	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:48
S69	3	("dPa" with viscosity) and paste and via and fill\$2 and (PCB or ((printed adj (circuit or wiring) adj board)))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:50
S70	3	("dPa" with viscosity) and paste and via and (PCB or ((printed adj (circuit or wiring) adj board)))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:53
S71	4	("dPa" with viscosity) and paste and via and board	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:51
S72	11	("dPa" with viscosity) and (PCB or ((printed adj (circuit or wiring) adj board)))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 10:53
S73	2	(via same fill\$3) and (paste with viscosity) and (grind\$3 with (buff or belt)) and (PCB or PWB or (printed adj (circuit or wiring) adj board))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 11:13
S74	11	(via same fill\$3) and (paste) and (grind\$3 with (buff or belt)) and (PCB or PWB or (printed adj (circuit or wiring) adj board))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2005/10/14 11:13